



Material Content Data Sheet



Sales Product Name		BTS7030-2EPA		Issued		12. February 2019		
MA#		MA004962540						
Package		PG-TSDSO-14-22		Weight*		64.99 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.139	1.75	1.75	17519	17519
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		145	
	non noble metal	zinc	7440-66-6	0.038	0.06		580	
	non noble metal	iron	7439-89-6	0.754	1.16		11602	
wire	non noble metal	copper	7440-50-8	30.617	47.11	48.34	471089	483416
	non noble metal	copper	7440-50-8	0.489	0.75	0.75	7530	7530
	encapsulation	organic material	carbon black	1333-86-4	0.087	0.13		1343
encapsulation	plastics	epoxy resin	-	3.404	5.24		52376	
	inorganic material	silicondioxide	60676-86-0	25.603	39.39	44.76	393936	447655
leadfinish	non noble metal	tin	7440-31-5	1.642	2.53	2.53	25259	25259
plating	noble metal	silver	7440-22-4	0.816	1.26	1.26	12556	12556
glue	plastics	epoxy resin	-	0.069	0.11		1061	
	noble metal	silver	7440-22-4	0.325	0.50	0.61	5004	6065
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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